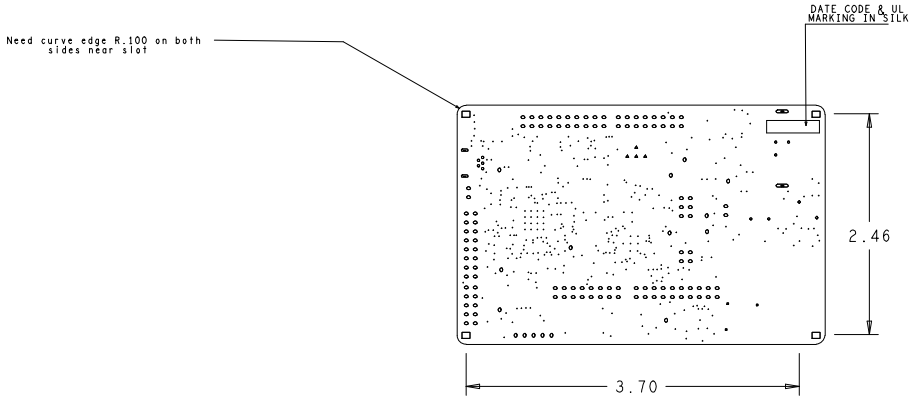
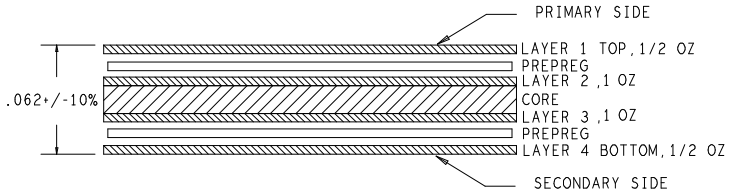
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
01	PROTO RELEASE	01/06/15	AKAP
02	ALPHA RELEASE	01/27/16	AKAP
03	BETA RELEASE	02/03/16	AKAP
04	ES10 RELEASE	02/09/16	AKAP
05	ES10 RELEASE	02/20/16	AKAP
06	ES10 RELEASE	02/26/16	AKAP



DRILL CHART: PSoC -48 Rev06				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
·	10.0	+3.0/-3.0	PLATED	397
•	15.7	+3.0/-3.0	PLATED	3
◦	25.6	+3.0/-3.0	PLATED	3
◦	27.6	+3.0/-3.0	PLATED	2
◦	28.0	+3.0/-3.0	PLATED	5
◦	31.5	+3.0/-3.0	PLATED	2
▲	35.4	+3.0/-3.0	PLATED	4
◦	40.2	+3.0/-3.0	PLATED	112
◦	42.9	+3.0/-3.0	PLATED	16
□	90.0	+2.0/-2.0	NON-PLATED	4
⬭	74.8x27.6	+3.0/-3.0	PLATED	2
⬭	135.0x35.0	+2.0/-2.0	NON-PLATED	2

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED.
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. REFER TO AS MENTIONED IN CROSS SECTION AREA IN THIS DOCUMENT.
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION DRAWING IN THE DOCUMENT.
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol.
      UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
      COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE
      BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE, LOGO AND RoHS COMPILANT SYMBOL IN SILKSCREEN ON SECONDARY SIDE.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE
      MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED
      ARE 1:1. SOLDERMASK COLOR **RED**
7. FINISH:
   A. SHALL BE IMMERSION GOLD(ENIG).
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY.
   FLAMABILITY RATING (94-V0).
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD
   IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN
      THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.



UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE
DIMENSIONS ARE IN INCHES	DRAWN PRAO	02/26/16
TOLERANCES ON: ANGLES +/- 2°	CHECKED AKAP	02/26/16
2 PL DECIMALS +/- .010	ENGRG AKAP	02/26/16
3 PL DECIMALS +/- .005	ISSUED	
THIRD ANGLE PROJECTIONS		

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CYPRESS SEMICONDUCTOR
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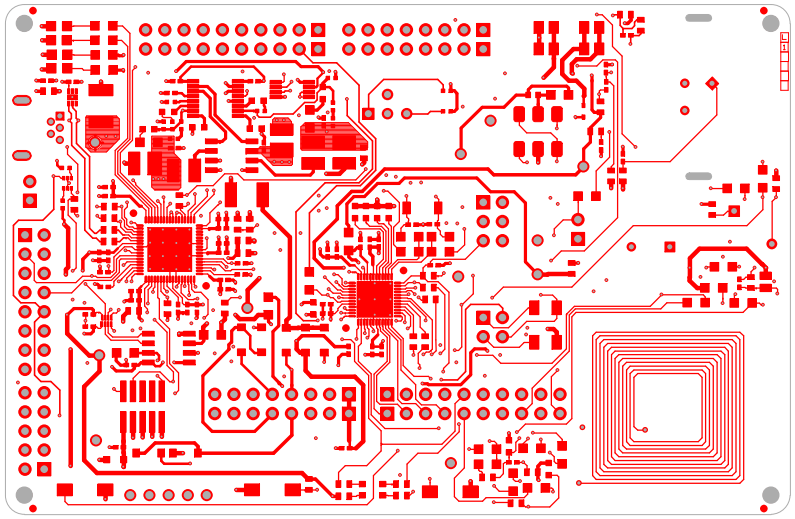
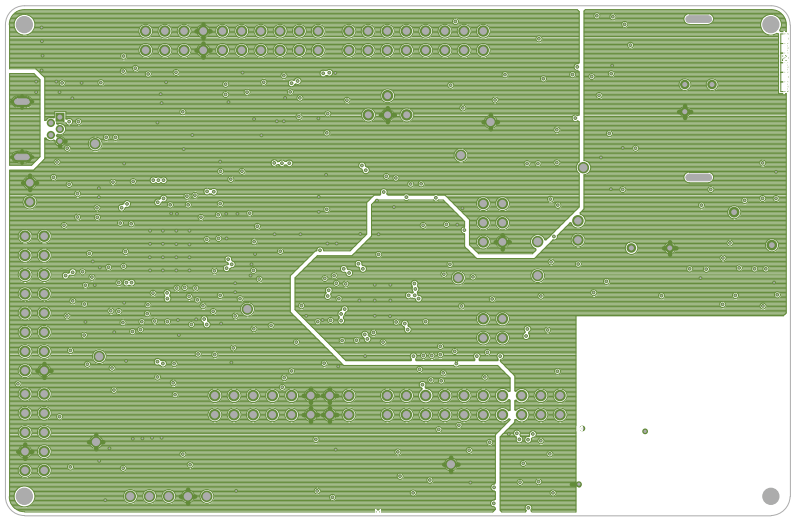
SAN JOSE, CA 95134
(408) 943-2600

FARICATION DRAWING
CY8CKIT-048 PSoC ANALOG COPROCESSOR KIT

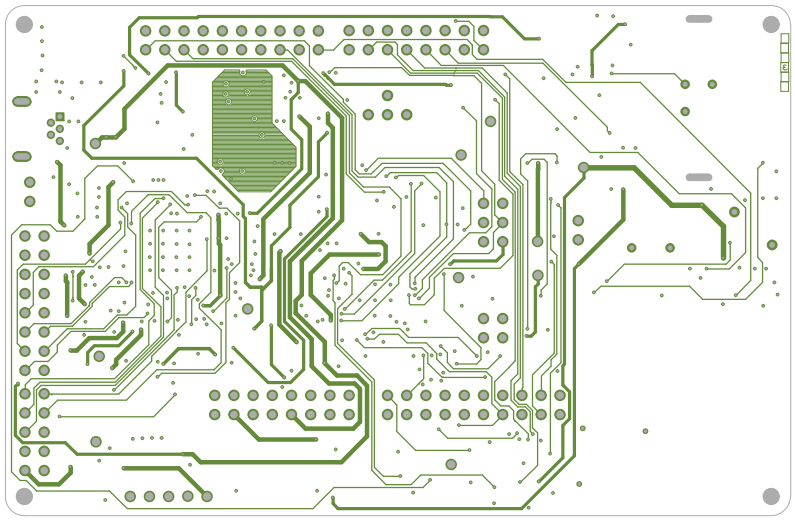
SIZE	FSCM NO	DWG NO	REV
	C	610-60294-01	06
SCALE:		SHEET:	



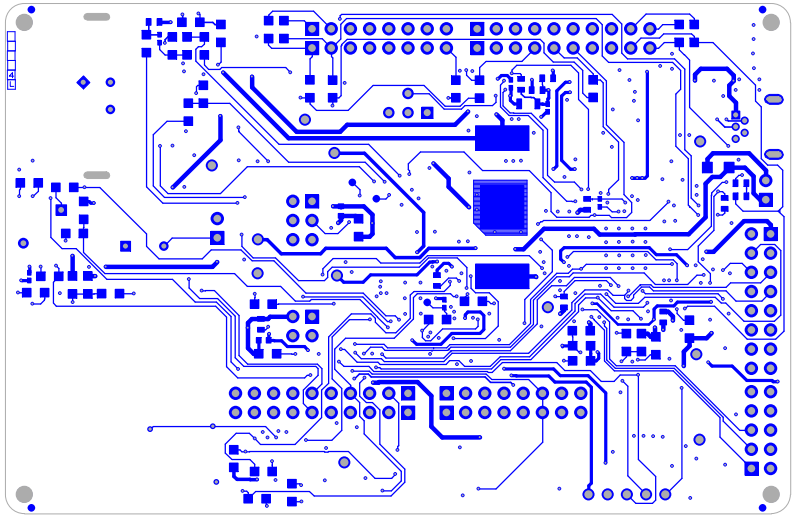
600-60319-01 REV06 PRIMARY SIDE



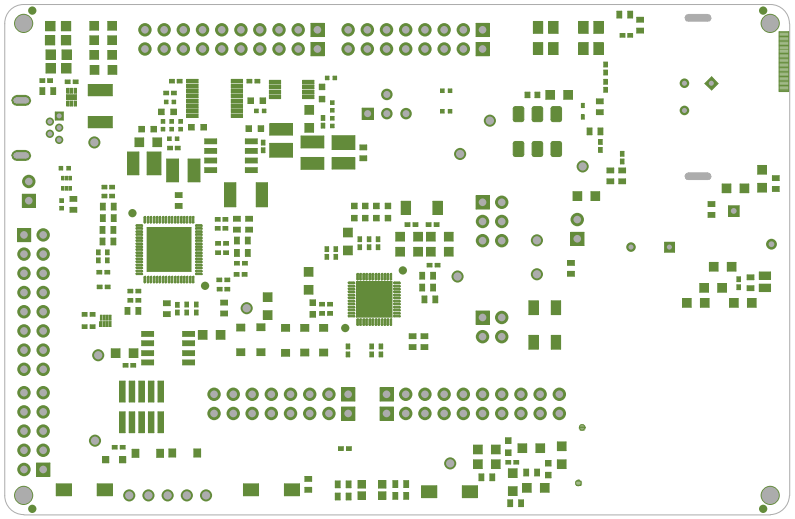
600-60319-01 REV06 GND LAYER



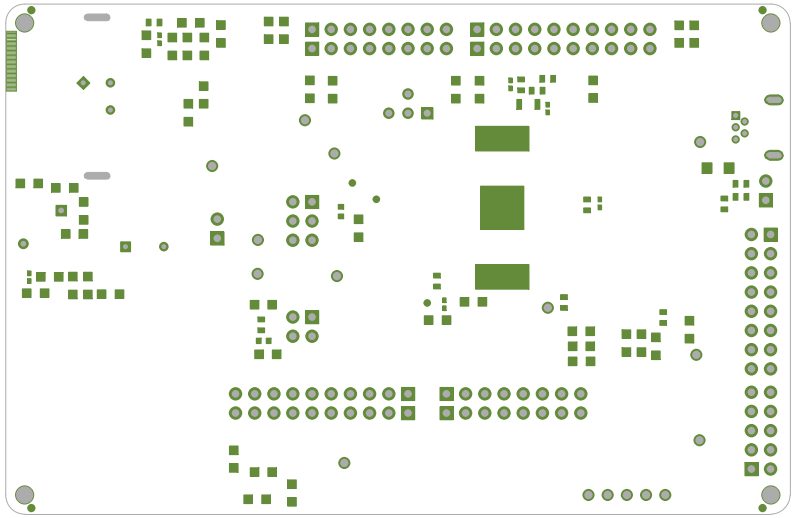
600-60319-01 REV06 POWER LAYER



600-60319-01 REV06 SECONDARY SIDE



600-60319-01 REV06 PRIMARY SOLDERMASK



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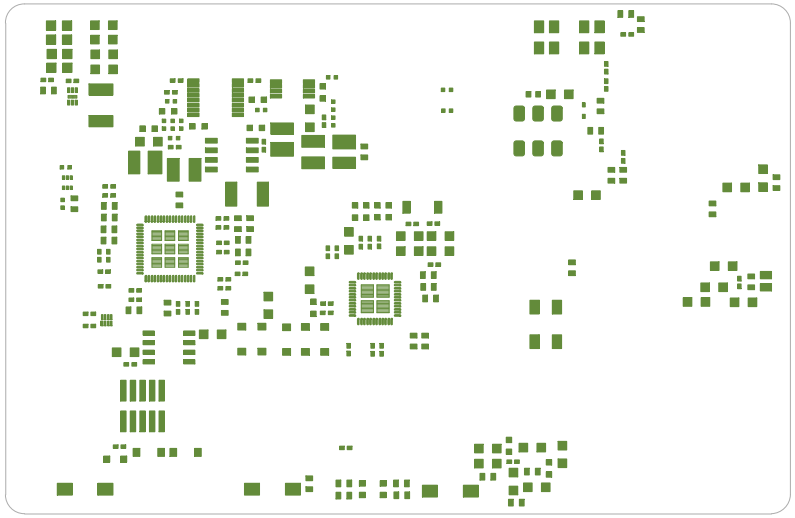
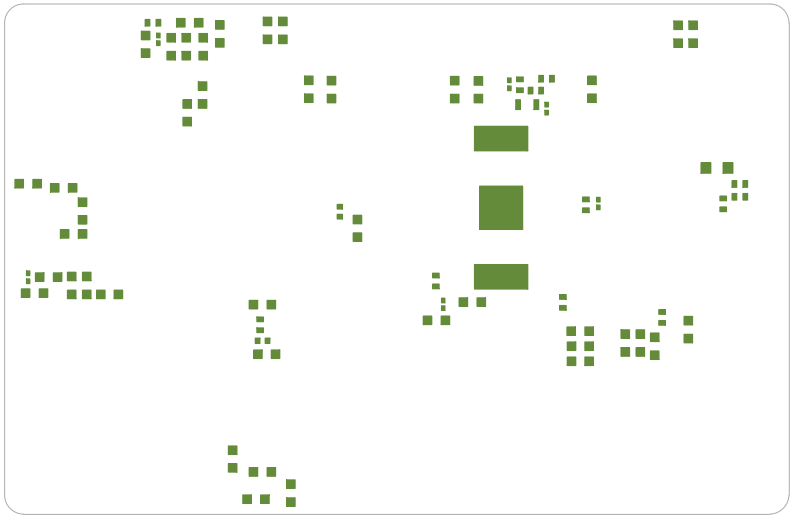


600-60319-01 REV06 PRIMARY SOLDERPASTE



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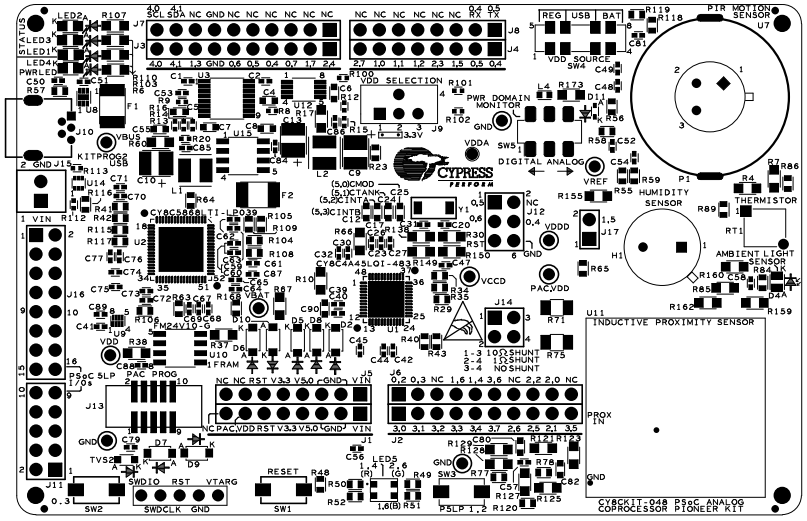
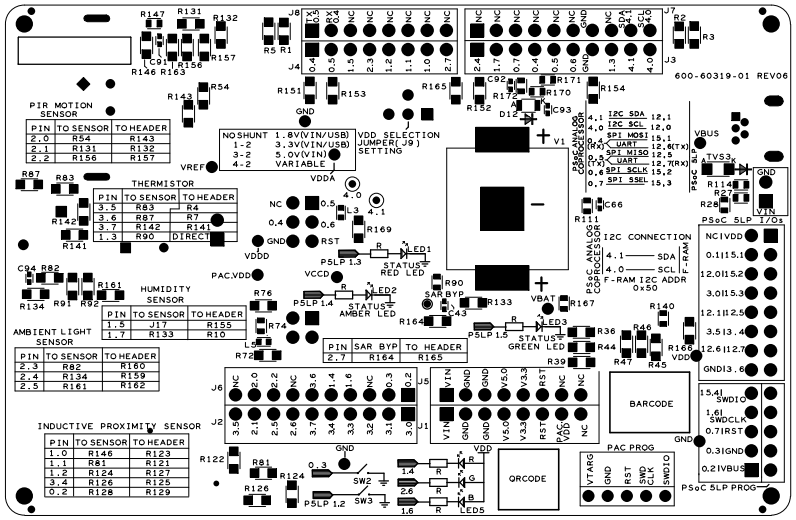


600-60319-01 REV06 PRIMARY SILKSCREEN



600-60319-01 REV06 SECONDARY SILKSCREEN